

ABSTRACT

A semiconductor component includes a thinned
5 semiconductor die having protective polymer layers on up to
six surfaces. The component also includes contact bumps on
the die embedded in a circuit side polymer layer, and
terminal contacts on the contact bumps in a dense area array.
A method for fabricating the component includes the steps of
10 providing a substrate containing multiple dice, forming
trenches on the substrate proximate to peripheral edges of
the dice, and depositing a polymer material into the
trenches. In addition, the method includes the steps of
15 planarizing the back side of the substrate to contact the
polymer filled trenches, and cutting through the polymer
trenches to singulate the components from the substrate.
Prior to the singulating step the components can be tested
and burned-in while they remain on the substrate.